



Product data sheet

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FEATURES

- Small surface mounting type
- High speed
- High reliability with high surge current handing capability

MARKING:A



SOD-523

Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C

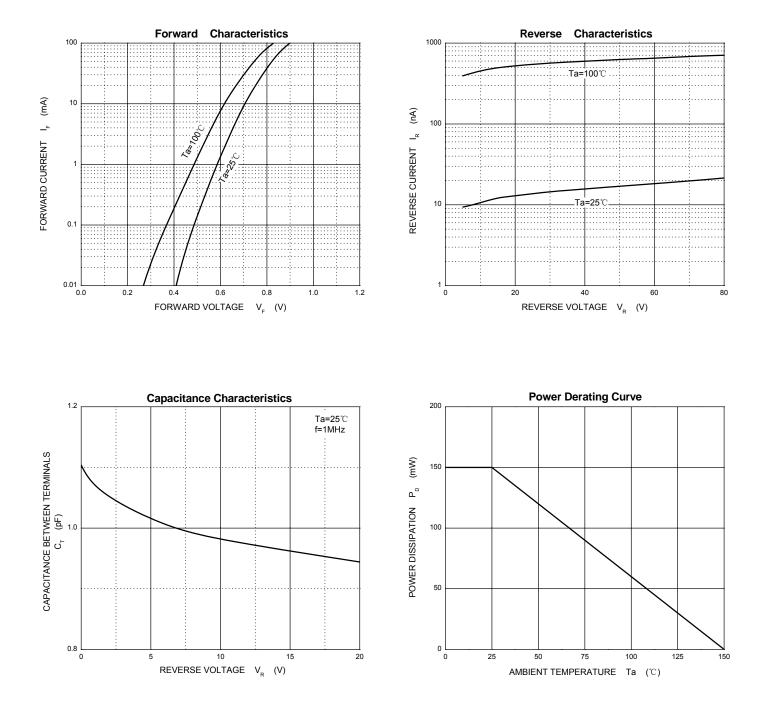
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	90	V
DC Blocking Voltage	V _R	80	V
Forward Continuous Current	I _{FM}	225	mA
Average Rectified Output Current	lo	100	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I _{FSM}	2.0	А
Power Dissipation	Pd	150	mW
Thermal Resistance Junction to Ambient	$R_{ extsf{ heta}JA}$	833	°C/W
Junction Temperature	Tj	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

Electrical Ratings @Ta=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V _F			1.2	V	I _F =100mA
Reverse current	I _R			0.1	μA	V _R =80V
Capacitance between terminals	Ст			3.0	pF	V _R =0.5V, f=1MHz
Reverse recovery time	t _{rr}			4	ns	V_R =6V,I _F =10mA,R _L =100 Ω



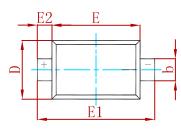
1SS400 HF Semiconductor Compiance

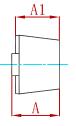


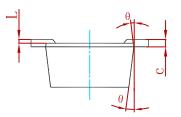




PACKAGE MECHANICAL DATA

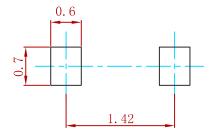






Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters. 2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
1SS400	SOD-523	3000





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